

Custom Tray Questionnaire

Contact	Title
Company	Tel
eMail	CC 1
Project/Component #	CC 2
A. Usage forecast:	
1. First time: Quantity of [] trays or [] number of com	ponents to be packaged
2. Yearly: Quantity of [] trays or [] number of components to be packaged	
B. Description of component:	
3. [] Attach outline drawing or sketch of your component (Required!)	
C. Maximum baking temperature of componen	ts in tray:
4. [] No Baking [] 50°C [] 75°C [] 125°C [] 140°C [] 150°C [] 180°C
D. Purpose (application) of tray: (Check all that apply	y)
5. [] In house usage [] Transport [] Pick and	Place to PC Board
E. Type of tray: 6. [] JEDEC Outline [] 2-Inch Waffle Pack []	4-inch Waffle Pack [] Other
F. Comments (Materials, color, stacking requirement, J.	EDEC and ESD requirements, etc):